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INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER

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## In the Specification

Please amend the first paragraph beginning on page 1, line 5, with the following rewritten paragragh:

This application is a Divisional of U.S. Application No. 09/650,569, filed August 30, 2000, now U.S. Patent No. 6,723,577, which is a Continuation of U.S. application, Serial No. 09/031,975, filed on February 26, 1998, now U.S. Patent No. 6,150,188, both of which are incorporated herein by reference.